

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1-8. (canceled).

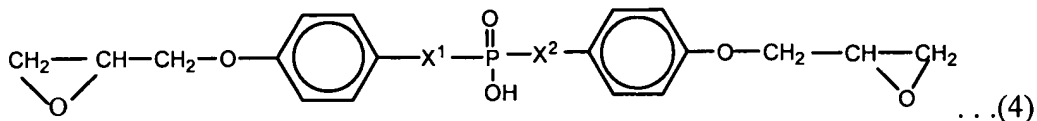
9. (previously presented): A multilayered printed circuit board comprising:
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer, wherein said solder resist layer contains an elastomer component in a composition comprising a resin for said solder resist layer, and
said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer.

10-31. (canceled).

32. (previously presented): A multilayered printed circuit board comprising:
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer, wherein said solder resist layer contains a P atom-containing epoxy resin,

said P atom-containing epoxy resin has bivalent phosphoric acid residue, and has epoxy groups in both terminals of the P atom-containing epoxy resin, and

said epoxy resin has the following general formula (4)

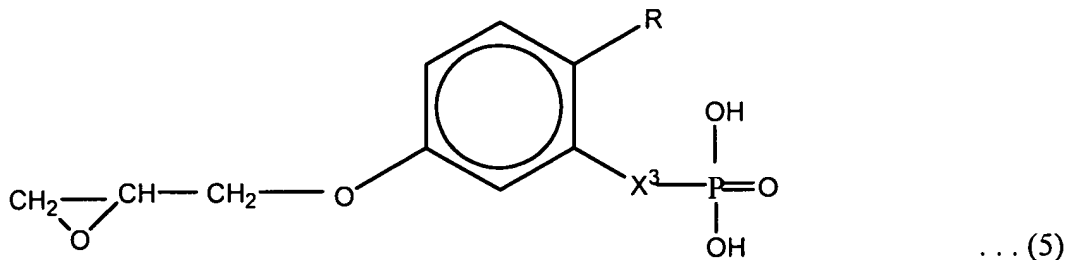


wherein X^1 and X^2 respectively represent O or a single bond.

33. (canceled) .

34. (previously presented): A multilayered printed circuit board comprising:
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,
wherein said solder resist layer contains a P atom-containing epoxy resin,
said P atom-containing epoxy resin is an epoxy resin having a monovalent phosphoric acid residue in one terminal of the P atom-containing epoxy resin and an epoxy group in the other terminal of the P atom-containing epoxy resin, and

said epoxy resin has the following general formula (5):



wherein X^3 represents O or a single bond; and R represents an alkyl of 2 to 8 carbons.

35. (canceled).

36. (previously presented): A multilayered printed circuit board comprising:
a conductor circuit and a resin insulating layer serially formed on a substrate in an
alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,
wherein said solder resist layer contains an elastomer component in a composition
comprising a resin for said solder resist layer,
said elastomer component is at least one member selected from the group consisting of
natural rubber, synthetic rubber, a thermoplastic resin and a thermosetting resin, and
said elastomer component is separated in micro-phase as to form an island-in-sea
structure after curing in said solder resist layer.

37-38. (canceled).

39. (previously presented): The multilayered printed circuit board according to claim
32,
wherein said solder resist layer contains at least one member selected from the group
consisting of a silicon compound, an aluminum compound and a magnesium compound.

40. (previously presented): The multilayered printed circuit board according to claim 34,
wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.